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**Samtec** **Expands** **ExaMAX® High-Speed Backplane Connector System With New Direct Mate Orthogonal (DMO) Options**

Orthogonal architecture offers improved SI performance and thermal efficiencies

**New Albany, IN:** Samtec, a privately held $662MM global manufacturer of a broad line of electronic interconnect solutions, proudly announces the expansion of the ExaMAX® High-Speed Backplane Connector System with new DMO options. System designers can now leverage the inherent advantages of direct mate orthogonal architectures when compared with traditional backplane systems.

Samtec’s new ExaMAX® DMO solutions offer system designers flexibility by removing the mid-plane, allowing fabric cards and line cards to mate directly. This fast-growing system architecture increases airflow and improves thermal efficiencies throughout the chassis. DMO solutions enhance signal integrity via shorter trace lengths and less connector transitions while streamlining the system BOM and optimizing system cost.

Samtec’s ExaMAX® DMO system consists of the new [EBDM-RA](https://www.samtec.com/products/ebdm-ra) series which mates directly with existing [EBTF-RA](https://www.samtec.com/products/ebtf-ra) series. Currently both 6 pair x 10 column and 6 pair x 12 column solutions are available. Guide pin and screw mount options are also available. 6 pair x 6 column and 6 pair x 8 column options are under development.

“Next generation system designers are quickly adopting DMO architectures,” said Jonathan Sprigler, Backplane Product Manager at Samtec, Inc. “Leading equipment vendors from across the data center industry - storage, server, networking and other applications – are leveraging the advantages of DMO via Samtec’s new EBDM-RA series.”

Samtec’s [EBDM-RA](https://www.samtec.com/products/ebdm-ra) series is but one solution from the ExaMAX® High-Speed Backplane Connector System. The ExaMAX® line of products are optimized for speeds up to 56 Gbps (PAM-4 modulation). Return loss compliance is achieved in both 85 Ω and 100 Ω systems due to targeting the 92 Ω specifications and controlling reflections at all geometry transitions within the connector.

ExaMAX® also has the industry’s lowest mating force with excellent normal force and meets Telcordia GR-1217 CORE specifications. With two reliable points of contact at all times, even when subjected to angled mating, residual stubs are minimized for improved signal integrity performance. A 2.4 mm contact wipe increases reliability while the hermaphroditic mating interface ensures stub-free mating and reliable alignment.

The backplane system features individual signal wafers with differential pairs in a staggered design and arranged in columns with zero skew. Each wafer includes a one-piece embossed ground structure, which increases isolation to significantly decrease crosstalk.

For more information, please watch the “[High-Speed Backplane Connectors Drive 56 Gbps and Beyond](http://www.eejournal.com/chalk_talks/high-speed-backplane-connectors-drive-56-gbps-and-beyond/)” webinar, visit the [ExaMAX® High-Speed Backplane Connector System](https://www.samtec.com/connectors/backplane/high-speed-backplane-systems/examax) landing page, or download the [High-Speed Board-to-Board Application Design Guide](http://suddendocs.samtec.com/literature/samtec-high-speed-b2b-design-guide.pdf). Immediate technical support is available from Samtec’s backplane applications experts at [HSBP@samtec.com](mailto:HSBP@samtec.com)**.**

**About Samtec, Inc.**

Founded in 1976, Samtec is a privately held, $662MM global manufacturer of a broad line of electronic interconnect solutions, including IC-to-Board and IC Packaging, High-Speed Board-to-Board, High-Speed Cables, Mid-Board and Panel Optics, Flexible Stacking, and Micro/Rugged components and cables. Samtec Technology Centers are dedicated to developing and advancing technologies, strategies and products to optimize both the performance and cost of a system from the bare die to an interface 100 meters away, and all interconnect points in between. With 33 locations in 18 different countries, Samtec’s global presence enables its unmatched customer service. For more information, please visit <http://www.samtec.com>.

ExaMAX® is a registered trademark of Amphenol Corporation.

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